

MB1M~MB10M

Rev.D May.-2017

/ Descriptions

0.8A MBM
0.8A DIP Glass Passivated Bridge Rectifier, MBM package.

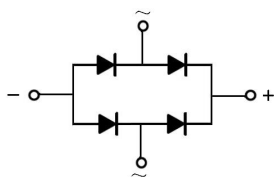
/ Features

Glass Passivated Chip Junction, Reverse Voltage:100to1000V, Forward Current: 0.8 A, High Surge Current Capability.

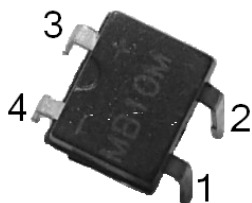
/ Applications

General purpose.

/ Equivalent Circuit



/ Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

/ Marking

See Marking Instructions.

Parameter	Symbol	Rating						Unit
		MB1M	MB2M	MB4M	MB6M	MB8M	MB10M	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at $T_a = 50^\circ\text{C}$	I_o	0.8						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	30						A
Typical Junction Capacitance ^(Note1)	C_j	13						pF
Typical Thermal Resistance ^{Note2}	$R_{\theta JA}$	95						/W
Typical Thermal Resistance ^{Note2}	$R_{\theta JL}$	30						/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55~+150						

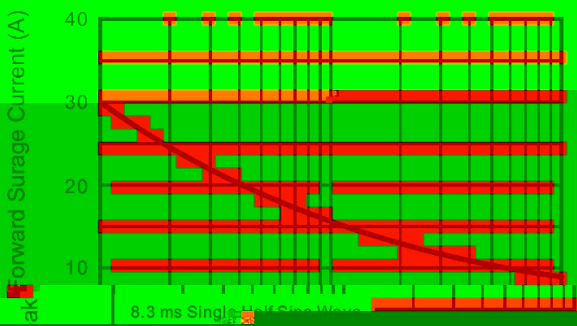
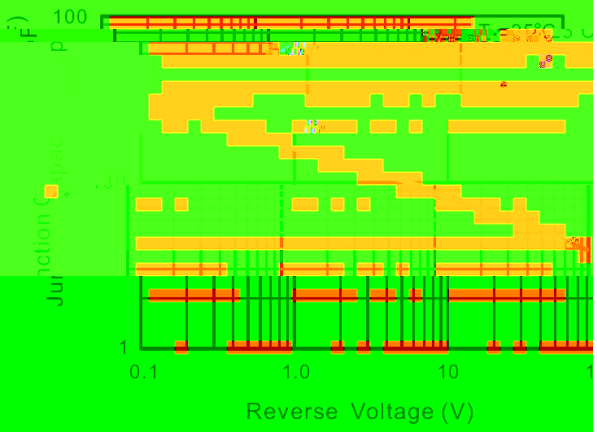
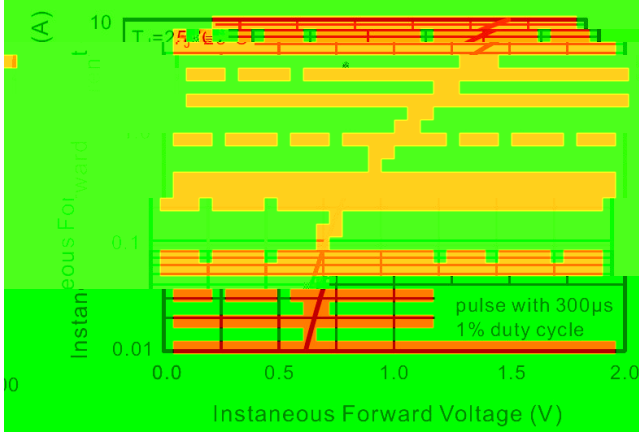
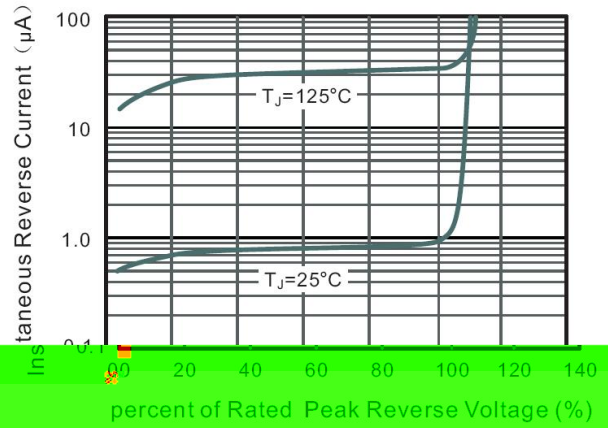
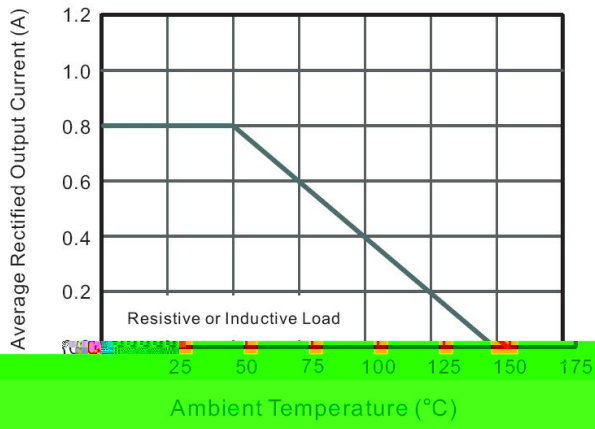
Note:

1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with $4 \times (5 \times 5\text{mm}^2)$ copper pad..

Parameter	Symbol	测试条件 Test condition	数值 Rating	单位 Unit
Maximum Forward Voltage	V_F	$I_F=0.4\text{A}$	1.0	V
		$I_F=0.8\text{A}$	1.1	

Maximum DC Reverse Current at Maximum DC

/ Electrical Characteristic Curve

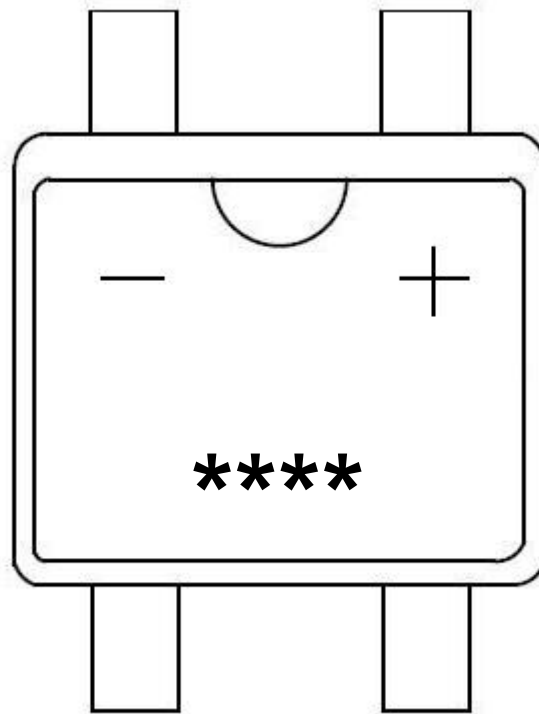


/ Marking Instructions

Marking

Type number	Marking code
MB1M	MB1M
MB2M	MB2M
MB4M	MB4M
MB6M	MB6M
MB8M	MB8M
MB10M	MB10M

/ Marking Instructions



MB1M

1 *

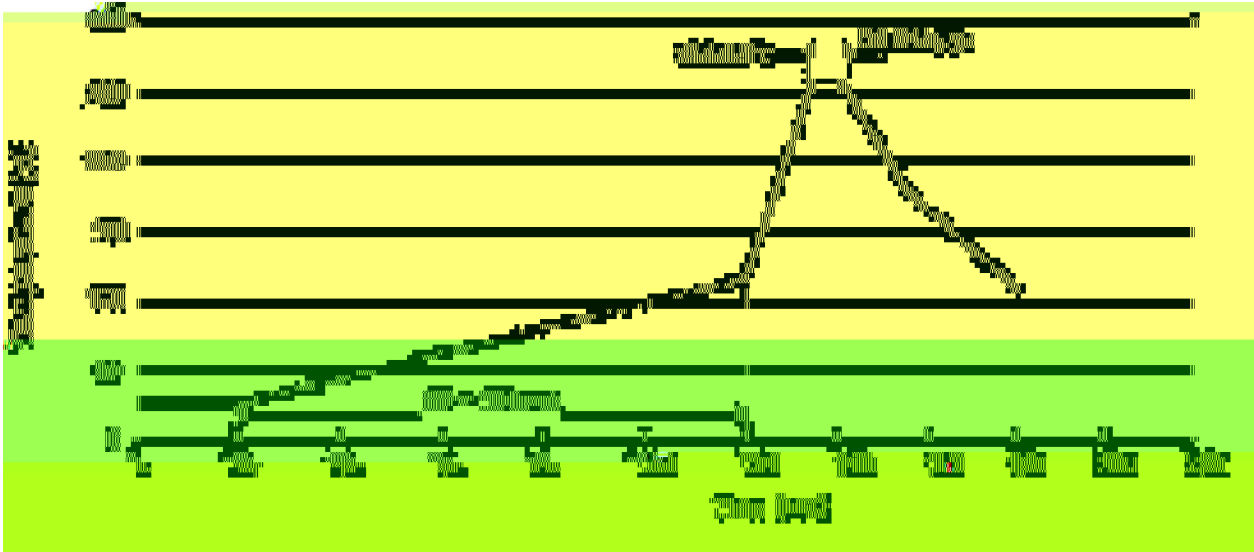
3 *

Note:

MB1M Product Type Code

**** Lot No. Code The 1st * means:YM Code The last 3 * means:little Lot No
Code

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-----|-----|----|----------|---|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255 | 5 | 5 | 0.5sec; | 2.Peak Temp.:255 5 , Duration:5 0.5sec. |
| 3 | | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

270 5 10 1 sec. Temp.:270 5 Time:10 1 sec

/ Packaging SPEC.

/ TUBE

Package Type	Units					Dimension (unit mm ³)		
	Units/Tube	Tubes/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Tube	Inner Box	Outer Box
MBM	100	50	5000	4	20000			

/ Notices